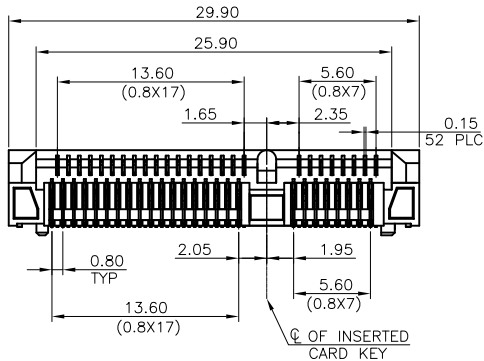
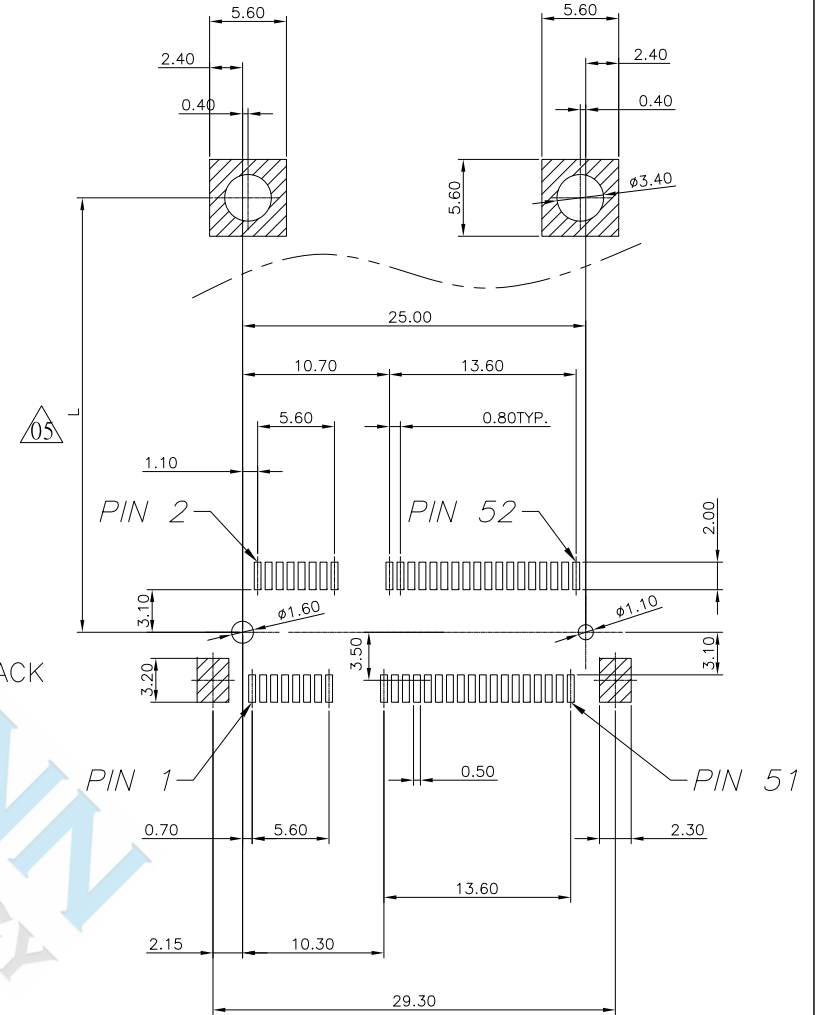


MODULE SIZE	L
HALF SIZE	23.9
FULL SIZE	48.05



**MATERIAL**

HOUSING : THERMO PLASTIC UL94V-0 BLACK

CONTACT : COPPER ALLOY

PEG : COPPER ALLOY

**SPECIFICATION**

CURRENT RATING : 0.5A 50V AC/DC

CONTACT RESISTANCE : 55 mΩ MAX

INSULATION RESISTANCE : 500 MΩ MIN AT 500V DC

OPERATING TEMPERATURE : -55°C~80°C

Recommended P.C.Board Layout.  
FOR STAND OFF TYPE

DIMENSIONS TOLERANCE METRIC	UNITS	MM	FINISH	SEE NOTE	CH'K	Calvin	DRAW NAME		WISCONN Technology Co., Ltd Tel:+886-2-2790-1979 Fax:+886-2-2790-1569						
Up to 5 ±0.2	QT'Y	N/A	DRAW	Johnson	APP'D	Selena	MINI PCI-E 本體 5.6H								
Above 5~15 ±0.3							PART NUMBER	WMPE-52FLBSR-56							
Above 15~30 ±0.4	MT'L	SEE NOTE	DE'N	Mike	DATE	August .17.2018	PART NUMBER	T057							
Above 30~50 ±0.5							SCALE	1/1	SIZE	A4	SHEET	1	REV.	A	
Angle ±0.3°							FILE NAME .DWG								